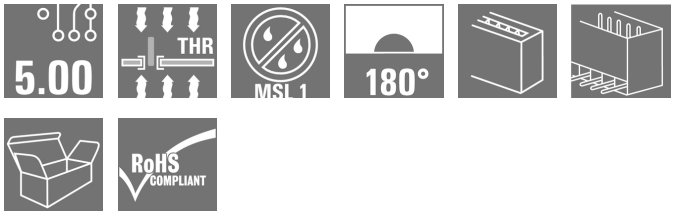
SL-SMT 5.00HC/20/180G 3.2SN BK BX

Weidmüller Interface GmbH & Co. KG
Klingenbergstraße 26
D-32758 Detmold
Germany

www.weidmueller.com

Product image





High-temperature-resistant pin header, packed in box or tape. On tape, with 1.5 mm solder pin, optimised for automatic assembly. 3.2 mm solder pin suitable for reflow and wave soldering. The pin headers provide space for labelling and can be coded. HC = High Current.

General ordering data

Version	PCB plug-in connector, male header, closed side, THT/THR solder connection, 5.00 mm, Number of poles: 20, 180°, Solder pin length (l): 3.2 mm, tinned, black, Box
Order No.	1841340000
Type	SL-SMT 5.00HC/20/180G 3.2SN BK BX
GTIN (EAN)	4032248352241
Qty.	20 pc(s).
Product data	IEC: 400 V / 27.5 A UL: 300 V / 18.5 A
Packaging	Box

Creation date September 16, 2022 6:56:49 PM CEST

SL-SMT 5.00HC/20/180G 3.2SN BK BX

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Technical data

Dimensions and weights

Depth	8.5 mm	Depth (inches)	0.335 inch
Height	15.2 mm	Height (inches)	0.598 inch
Height of lowest version	12 mm	Width	103.2 mm
Width (inches)	4.063 inch	Net weight	8.9 g

System specifications

Product family	OMNIMATE Signal - series BL/SL 5.00	Type of connection	Board connection
Mounting onto the PCB	THT/THR solder connection	Pitch in mm (P)	5 mm
Pitch in inches (P)	0.197 inch	Outgoing elbow	180°
Number of poles	20	Number of solder pins per pole	1
Solder pin length (l)	3.2 mm	Solder pin length tolerance	+0.1 / -0.2 mm
Solder pin dimensions	d = 1.2 mm, Octagonal	Solder pin dimensions = d tolerance	0 / -0,03 mm
Solder eyelet hole diameter (D)	1.5 mm	Solder eyelet hole diameter tolerance (D)	+ 0,1 mm
L1 in mm	95 mm	L1 in inches	3.74 inch
Number of rows	1	Pin series quantity	1
Protection degree	IP20	Volume resistance	≤5 mΩ
Can be coded	Yes	Plugging force/pole, max.	7 N
Pulling force/pole, max.	5.5 N		

Material data

Insulating material	LCP GF	Colour	black
Colour chart (similar)	RAL 9011	Insulating material group	IIIa
Comparative Tracking Index (CTI)	≥ 175	Moisture Level (MSL)	1
UL 94 flammability rating	V-0	Contact material	CuMg
Contact surface	tinned	Layer structure of solder connection	1...3 µm Ni / 2...4 µm Sn matt
Layer structure of plug contact	1...3 µm Ni / 2...4 µm Sn matt	Storage temperature, min.	-40 °C
Storage temperature, max.	70 °C	Operating temperature, min.	-50 °C
Operating temperature, max.	100 °C	Temperature range, installation, min.	-30 °C
Temperature range, installation, max.	100 °C		

Rated data acc. to IEC

tested acc. to standard	IEC 60664-1, IEC 61984	Rated current, min. number of poles (Tu=20°C)	27.5 A
Rated current, max. number of poles (Tu=20°C)	19 A	Rated current, min. number of poles (Tu=40°C)	24 A
Rated current, max. number of poles (Tu=40°C)	16.5 A	Rated voltage for surge voltage class / pollution degree II/2	400 V
Rated voltage for surge voltage class / pollution degree III/2	320 V	Rated voltage for surge voltage class / pollution degree III/3	250 V
Rated impulse voltage for surge voltage class/ pollution degree II/2	4 kV	Rated impulse voltage for surge voltage class/ pollution degree III/2	4 kV
Rated impulse voltage for surge voltage class/ contamination degree III/3	4 kV		

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Technical data

Rated data acc. to CSA

Institute (CSA)		Certificate No. (CSA)	200039-1176845
Rated voltage (Use group B / CSA)	300 V	Rated voltage (Use group D / CSA)	300 V
Rated current (Use group B / CSA)	15 A	Rated current (Use group D / CSA)	15 A
Reference to approval values	Specifications are maximum values, details - see approval certificate.		

Packing

Packaging	Box	VPE length	141 mm
VPE width	127 mm	VPE height	30 mm

Classifications

ETIM 6.0	EC002637	ETIM 7.0	EC002637
ETIM 8.0	EC002637	ECLASS 9.0	27-44-04-02
ECLASS 9.1	27-44-04-02	ECLASS 10.0	27-44-04-02
ECLASS 11.0	27-46-02-01	ECLASS 12.0	27-46-02-01

Important note

IPC conformity	Conformity: The products are developed, manufactured and delivered according international recognized standards and norms and comply with the assured properties in the data sheet resp. fulfill decorative properties in accordance with IPC-A-610 "Class 2". Further claims on the products can be evaluated on request.
Notes	• Gold-plated contact surfaces on request • Rated current related to rated cross-section & min. No. of poles. • Diameter of solder eyelet D = 1.4+0.1mm • Solder eyelet diameter D = 1.5 + 0.1 mm, from 9 poles • P on drawing = pitch • Rated data refer only to the component itself. Clearance and creepage distances to other components are to be designed in accordance with the relevant application standards. • Long term storage of the product with average temperature of 50 °C and average humidity 70%, 36 months

Approvals

Approvals	
ROHS	Conform
UL File Number Search	UL Website
Certificate No. (UR)	E60693

SL-SMT 5.00HC/20/180G 3.2SN BK BX

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Technical data

Downloads

Approval/Certificate/Document of Conformity	Declaration of the Manufacturer
Engineering Data	CAD data – STEP
Catalogues	Catalogues in PDF-format
Brochures	FL DRIVES EN MB SMT EN FL DRIVES DE MB DEVICE MANUF. EN FL BUILDING SAFETY EN FL APPL LED LIGHTING EN FL INDUSTR.CONTROLS EN FL MACHINE SAFETY EN FL HEATING ELECTR EN FL APPL_INVERTER EN FL_BASE_STATION_EN FL ELEVATOR EN FL POWER SUPPLY EN FL 72H SAMPLE SER EN PO OMNIMATE EN PO OMNIMATE EN
White paper surface mount technology	Download Whitepaper

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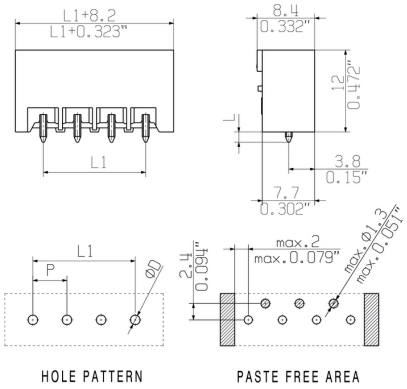
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Drawings

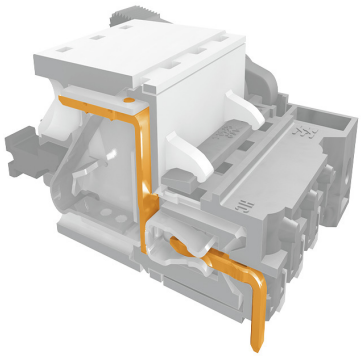
Product image



Dimensional drawing



Product benefits



Safe power transmission
Proven properties

SL-SMT 5.00HC/20/180G 3.2SN BK BX

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Drawings

Product benefits

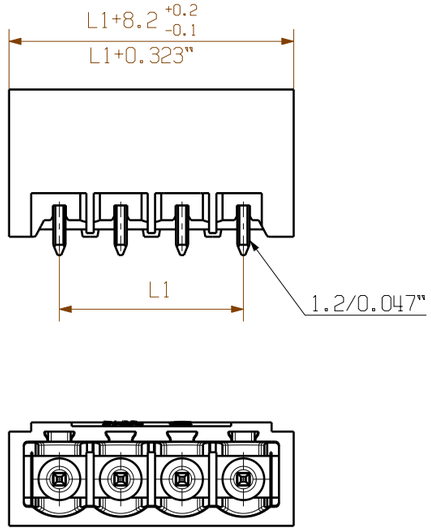


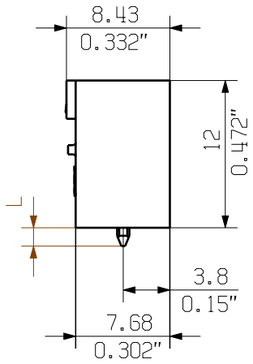
Compliant with existing standards

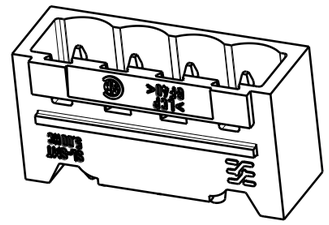
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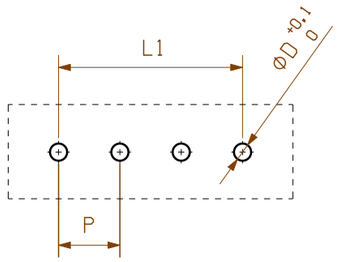
Dimensions without tolerances are no check dimensions

The English version is binding

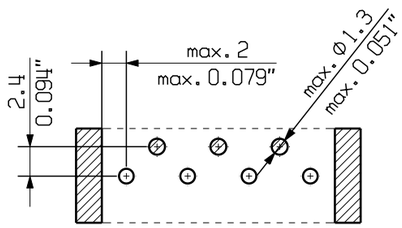








HOLE PATTERN



PASTE FREE AREA

n	L1 [mm]	L1 [Inch]
24	115,00	4,528
23	110,00	4,331
22	105,00	4,134
21	100,00	3,937
20	95,00	3,740
19	90,00	3,543
18	85,00	3,346
17	80,00	3,150
16	75,00	2,953
15	70,00	2,756
14	65,00	2,559
13	60,00	2,362
12	55,00	2,165
11	50,00	1,969
10	45,00	1,772
9	40,00	1,575
8	35,00	1,378
7	30,00	1,181
6	25,00	0,984
5	20,00	0,787
4	15,00	0,591
3	10,00	0,394
2	5,00	0,197

STIFTLAENGE L	TOLERANZ
1,5	0,0
	-0,3
3,2	0,1
	-0,3

D= 1.4/0.055" or 1.5/0.059"(REFLOW SOLDERING)
RECOMMENDATION FOR AUTOMATIC ASSEMBLY
(1.4mm FOR n=2...8 / 1.5mm for n=9...24)

P= RASTER/PITCH

SHOWN: SL-SMT 5.00HC/04/180 G

For the mounting of PCBs, it should be noted that the rated data stated here relates only to the PCB components alone.
The neccessary creepage and clearance paths must be observed in connection with the respective applicant in accordance to IEC 664 / VDE 0110.
The current-carrying capacity and pitch tolerance is to be determined according to DIN IEC 326 part 3 very fine.

Weidmüller PCB components are tested to the DIN EN 61984 standard, and are valid for its field of application.
Provided that the components are used to the intended purpose, all requirements with respect to the occuring of electrical, mechanical, thermic and corrosive stress will be satisfied.

RoHS COMPLIANT

DIN ISO 2768-m

106340/4
30.07.18 HERTEL_S 00
.

Modification

. . Cat.no.: .

Weidmüller

C 34165 07
Drawing no. Issue no.

Sheet 02 of 04 sheets

	Date	Name
Drawn	22.01.2008	HERTEL_S
Responsible		HERTEL_S
Checked	27.08.2018	HERTEL_S
Approved		LANG_T

Scale: 2/1

Supersedes: .

SL-SMT 5.00HC/../180...

STIFTLEISTE
PIN HEADER

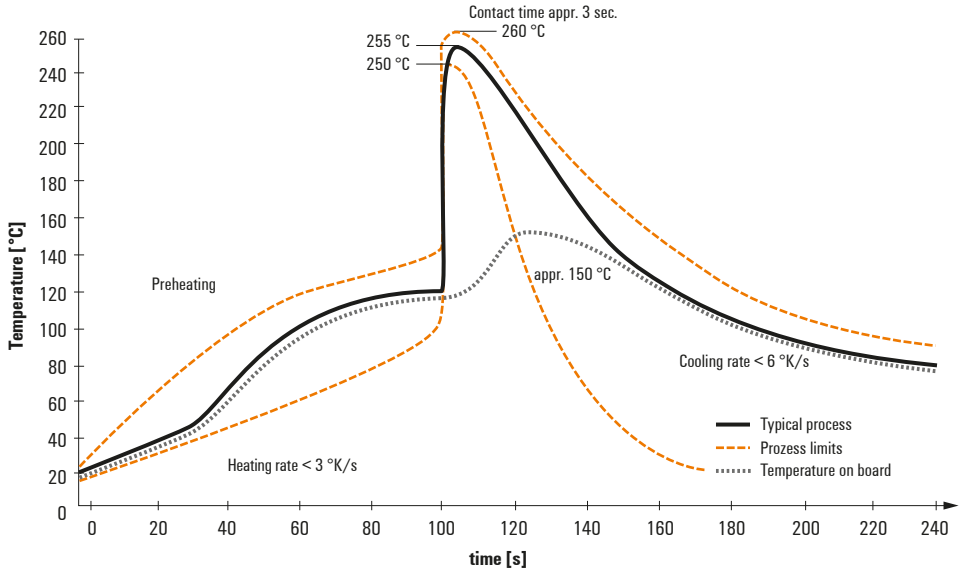
Product file: SL-SMT 5.00 7279

Wave Solder Profile

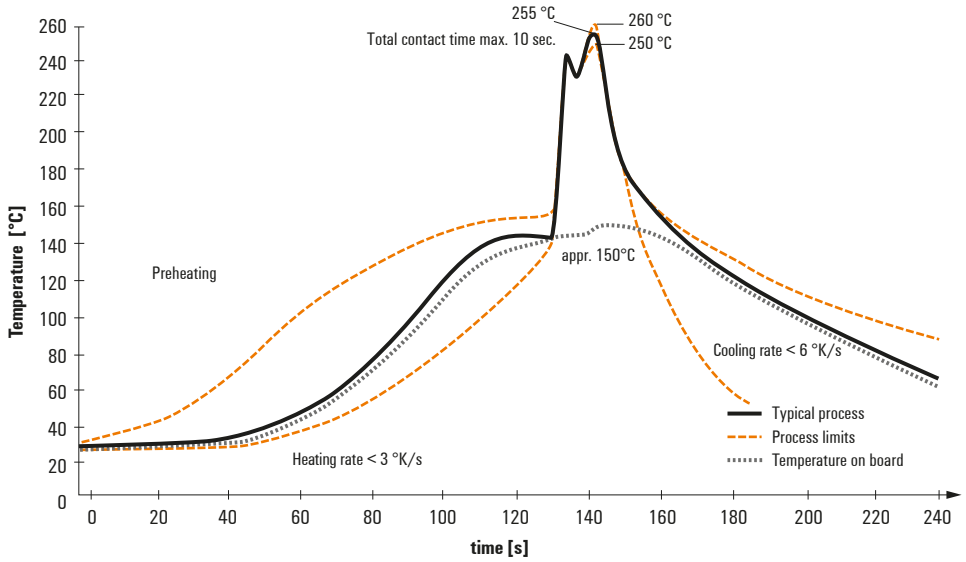
Recommended wave solderding profiles

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Fax: +49 5231 14-292083
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Single Wave:



Double Wave:



Wave soldering profiles

Wired connection elements should be processed in accordance with the DIN EN 61760-1 standard. We have included two recommendations for practical wave soldering profiles, with which Weidmüller PCB terminals and connectors are qualified.

When choosing a suitable profile for your application, the following factors also need to be considered:
- PCB thickness
- Proportion of Cu in the layers
- Single/double-sided assembly
- Product range
- Heating and cooling rates

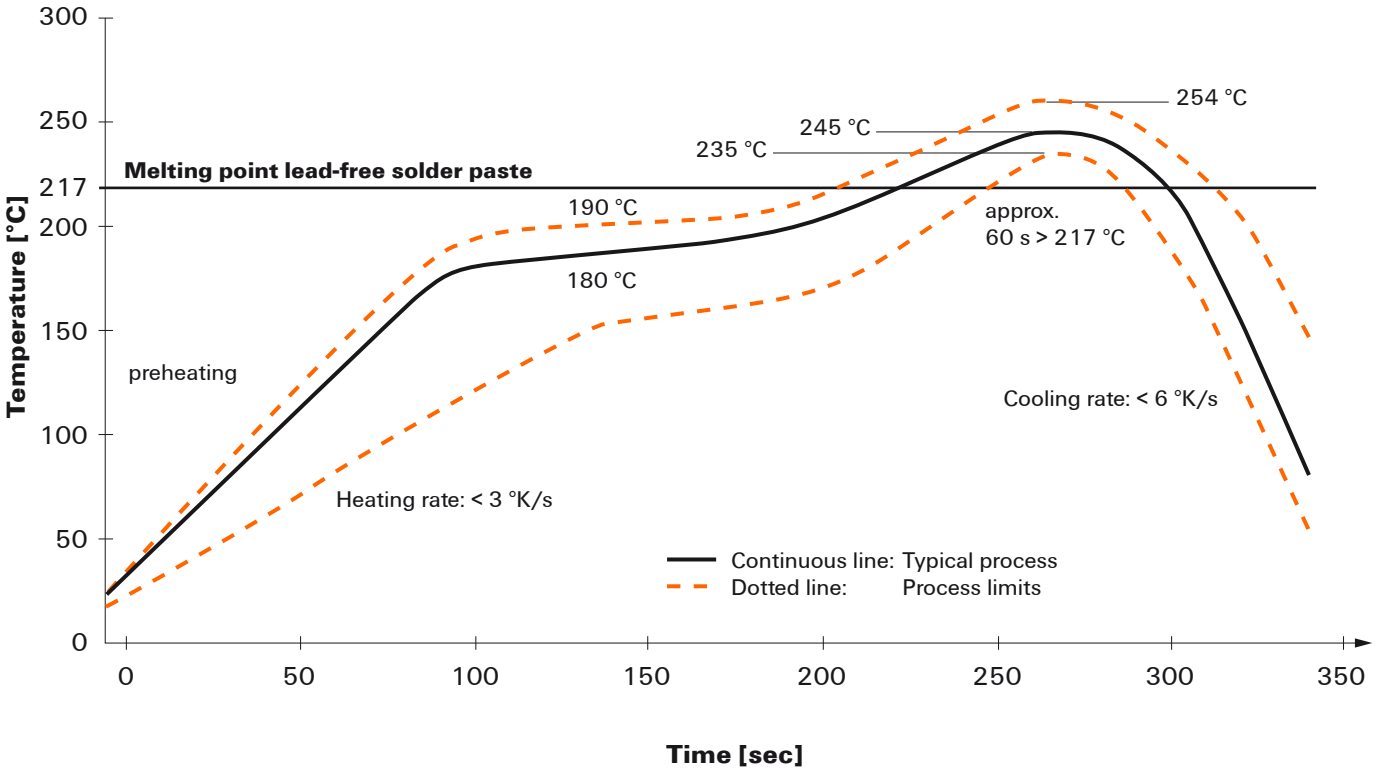
The single and double wave profiles each indicate the recommended operating range, including the maximum soldering temperature of 260°C. In practice, the maximum soldering temperature is quite often well below the above maximum profile.

We reserve the right to make technical changes.

Reflow Solder Profile

Recommended reflow soldering profile

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Reflow soldering profile

The perfect soldering profile for SMT Surface Mount Technology is one the most exiting question in SMT production. But there are more than one correct answer: The diagram of temperature-on-time is related to processing features of solder paste and to maximum load of components.

We have to consider the following parameters:
- Time for pre heating
- Maximum temperature
- Time above melting point
- Time for cooling
- Maximum heating rate
- Maximum cooling rate

We recommend a typical solder profile with associated process limits. With preheating components and board are prepared smoothly for the solder phase. Heating rate is typically ≤ +3K/s. In parallel the solder paste is ‚activated'. The time above melting point of 217°C the paste gets liquid and components and boards begin to connect. The maximum temperature of 245°C to 254°C should stay between 10 and 40 seconds. In the cooling phase at ≥ -6K/s solder is cured. Board and components cool down while avoiding cold cracks.

We reserve the right to make technical changes.